

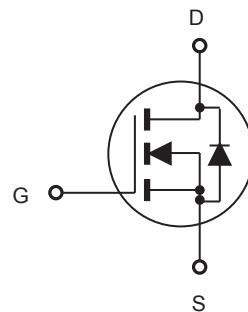


CEDF634/CEUF634

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 250V, 6.7A, $R_{DS(ON)} = 450\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.

CEU SERIES
TO-252(D-PAK)CED SERIES
TO-251(I-PAK)

ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	250	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	6.7	A
Drain Current-Pulsed ^a	I_{DM}	26	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	46 0.37	W W/ $^\circ\text{C}$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	R_{JC}	2.7	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	R_{JA}	50	$^\circ\text{C}/\text{W}$



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	250			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 250\text{V}, V_{\text{GS}} = 0\text{V}$			25	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 3.5\text{A}$			450	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 50\text{V}, I_D = 5.1\text{A}$		4.4		S
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		925		pF
Output Capacitance	C_{oss}			95		pF
Reverse Transfer Capacitance	C_{rss}			20		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 125\text{V}, I_D = 5.6\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 12\Omega$		16	32	ns
Turn-On Rise Time	t_r			3.5	7	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			38	76	ns
Turn-Off Fall Time	t_f			4	8	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 200\text{V}, I_D = 5.6\text{A}, V_{\text{GS}} = 10\text{V}$		18	23	nC
Gate-Source Charge	Q_{gs}			3		nC
Gate-Drain Charge	Q_{gd}			5		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				6.7	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 6.7\text{A}$		0.9	1.5	V
Notes :						
a.Repetitive Rating : Pulse width limited by maximum junction temperature. b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$. c.Guaranteed by design, not subject to production testing. d.UIS condition $V_{\text{dd}}=25\text{V}$ $L=2\text{mH}$ $R_{\text{g}}=25\text{ohm}$ $I_{\text{as}}=6.7\text{A}$.						

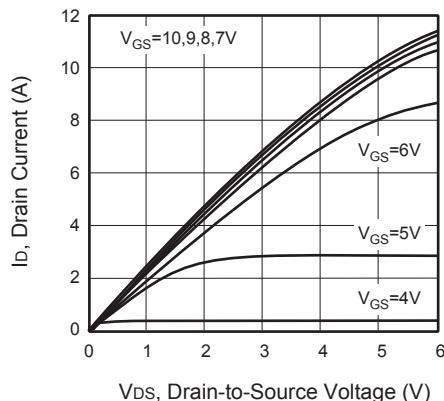


Figure 1. Output Characteristics

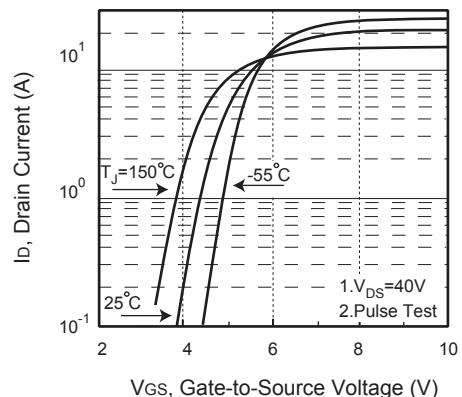


Figure 2. Transfer Characteristics

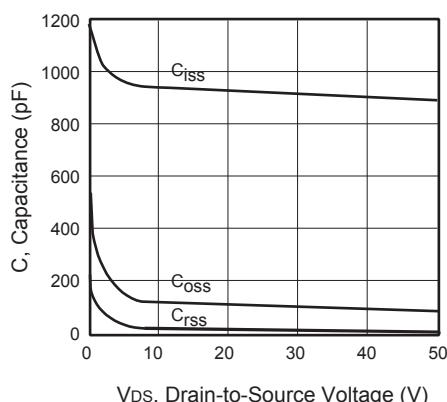


Figure 3. Capacitance

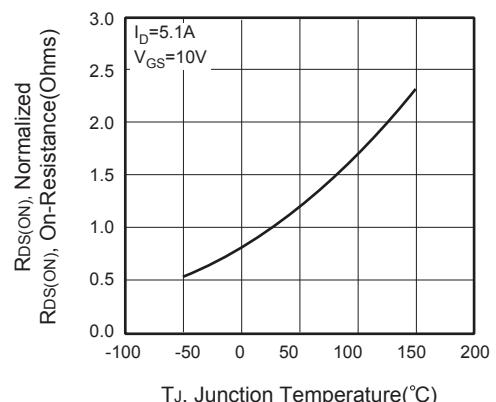


Figure 4. On-Resistance Variation with Temperature

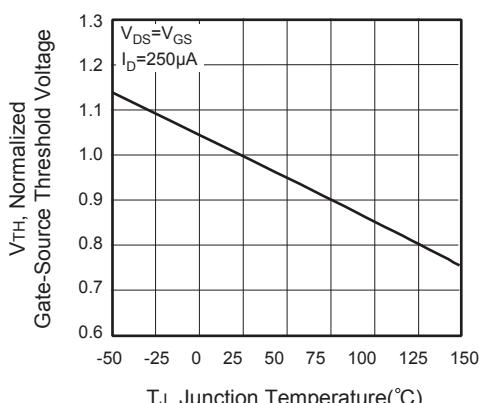


Figure 5. Gate Threshold Variation with Temperature

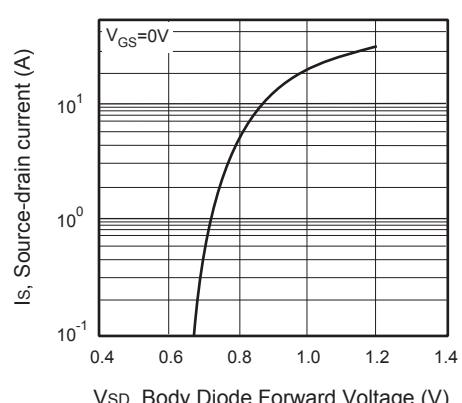


Figure 6. Body Diode Forward Voltage Variation with Source Current



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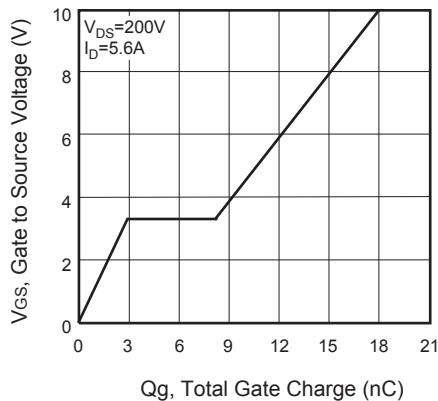


Figure 7. Gate Charge

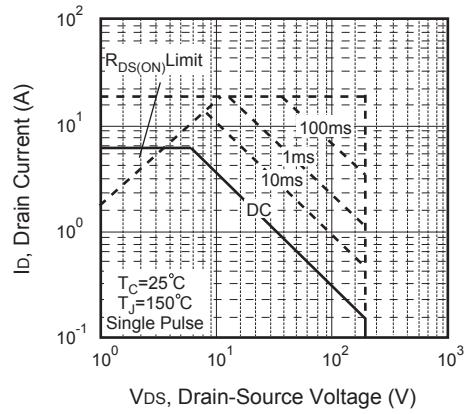


Figure 8. Maximum Safe Operating Area

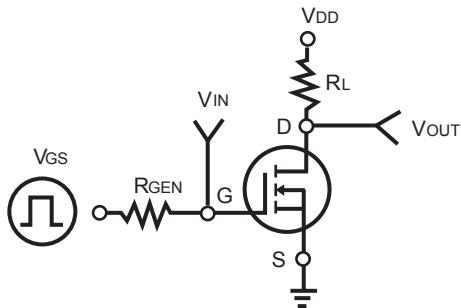


Figure 9. Switching Test Circuit

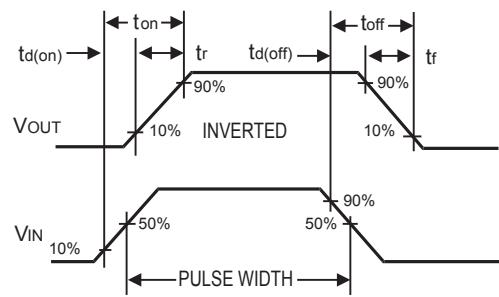


Figure 10. Switching Waveforms

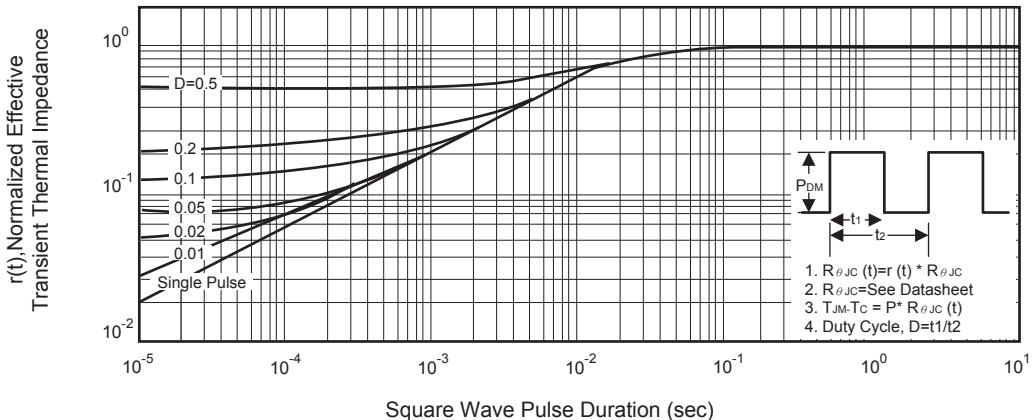


Figure 11. Normalized Thermal Transient Impedance Curve